- Package Options Include Plastic "Small Outline" Packages, Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

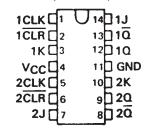
description

The '73, and 'H73, contain two independent J-K flip-flops with individual J-K, clock, and direct clear inputs. The '73, and 'H73, are positive pulse-triggered flip-flops. J-K input is loaded into the master while the clock is high and transferred to the slave on the high-to-low transition. For these devices the J and K inputs must be stable while the clock is high.

The 'LS73A contains two independent negative-edge-triggered flip-flops. The J and K inputs must be stable one setup time prior to the high-to-low clock transition for predictable operation. When the clear is low, it overrides the clock and data inputs forcing the Ω output low and the $\overline{\Omega}$ output high.

The SN5473, SN54H73, and the SN54LS73A are characterized for operation over the full military temperature range of -55 °C to 125 °C. The SN7473, and the SN74LS73A are characterized for operation from 0 °C to 70 °C.

SN5473, SN54LS73A . . . J OR W PACKAGE SN7473 . . . N PACKAGE SN74LS73A . . . D OR N PACKAGE (TOP VIEW)



73
FUNCTION TABLE

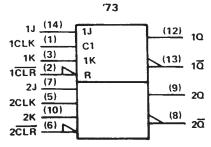
	INPUT	S		OUT	PUTS
CLR	CLK	J	K	Q	ā
L	×	Х	Х	L	Н
Н	Ţ	L	L	00	\bar{a}_0
Н	工	Н	L	Н	L
Н	ъ.	L	Н	L	Н
Н	T	Н	Н	TOG	GLE

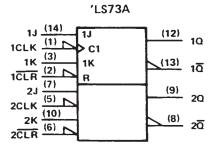
'L\$73A FUNCTION TABLE

	INPUT	rs		OUTP	UTS
CLR	CLK	J	K	Q	₫
L	X	Х	Х	L	Н
н	1	L	L	αo	\overline{a}_{O}
н	1	Н	L	Н	L
н	1	L	Н	L	н
н	1	Н	Н	TOG	GLE
н	Н	Х	Х	αo	\bar{a}_0

FOR CHIP CARRIER INFORMATION.
CONTACT THE FACTORY

logic symbols†



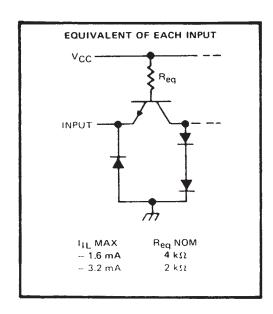


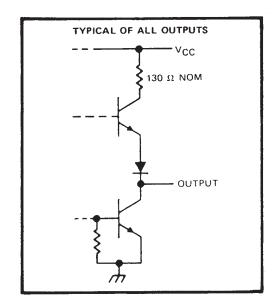
[†]These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

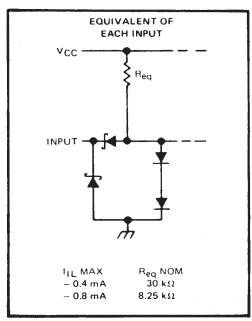
′73

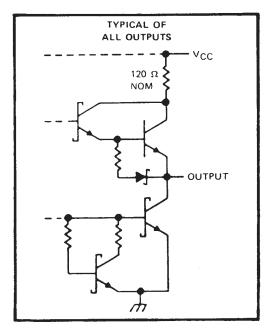
'LS73

schematics of inputs and outputs

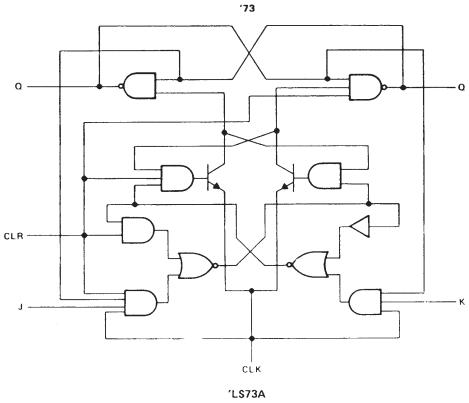


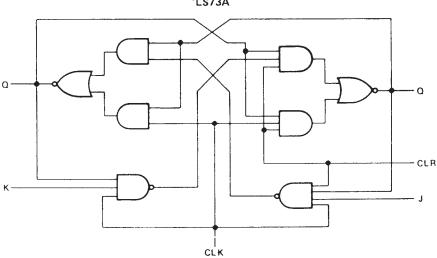






logic diagrams (positive logic)





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (See Note 1)		7 V
Input voltage: '73		5.5 V
′LS73A		7 V
Operating free-air temperature range:	SN54'	-55°C to 125°C
operating that an early are a series of	SN74'	0° C to 70°C

NOTE 1: Voltage values are with respect to network ground terminal.



SN5473, SN54LS73A, SN7473, SN74LS73A DUAL J-K FLIP-FLOPS WITH CLEAR

SDLS118 - DECEMBER 1983 - REVISED MARCH 1988

recommended operating conditions

				SN547	3		SN747	3	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNII
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	٧
VIH	High-level input voltage		2			2			>
VIL	Low-level input voltage				8.0			0.8	٧
ЮН	High-level output current				-0.4			- 0.4	mA
loL	Low-level output current				16			16	mA
		CLK high	20			20			
tw	Pulse duration	CLK low	47			47			ns
		CLR low	25			25			
t _{su}	Input setup time before CLK f		0			0			ns
th	Input hold time data after CLK↓		0			0			ns
TA	Operating free-air temperature		- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				unt.		SN5473			SN7473		
PA	RAMETER	TEST CONDITIONS†				TYP#	MAX	MIN	TYP‡	MAX	UNIT
VIK		V _{CC} = MIN,	I _I = - 12 mA				- 1.5			- 1.5	V
Vон		V _{CC} = MIN, I _{OH} = - 0.4 mA	V _{IH} = 2 V,	V _{IL} = 0.8 V,	2.4	3.4		2.4	3.4		٧
VOL		V _{CC} = MIN, I _{OL} = 16 mA	V _{IH} = 2 V,	V _{IL} = 0.8 V,		0.2	0.4		0.2	0.4	V
11		V _{CC} = MAX,	V _I = 5.5 V				1			1	mA
ЧН	J or K	V _{CC} = MAX,	V ₁ = 2.4 V				40 80			40 80	μА
	J or K						- 1.6			- 1.6	
ItL	CLR	V _{CC} = MAX,	V ₁ = 0.4 V				- 3,2			- 3.2	mA
	CLK		·				- 3.2			- 3.2	}
los§		V _{CC} = MAX			- 20		– 57	- 18		- 57	mA
Icc¶		V _{CC} = MAX,	See Note 2			10	20	<u> </u>	10	20	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: With all outputs open, I_{CC} is measured with the Q and \overline{Q} outputs high in turn. At the time of measurement, the clock input is grounded.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER#	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f _{max}				15	20		MHz
^t PLH	CLR	₫ .			16	25	ns
^t PHL	CLA	Q	$R_L = 400 \Omega$, $C_L = 15 pF$	-	25	40	กร
^t PLH	CLK	Q or Q			16	25	ns
^t PHL	CLK	2 07 02			25	40	ns

[#]f_{max} = maximum clock frequency: tp_{LH} = propagation delay time, low-to-high-level output; tp_{HL} = propagation delay time, high-to-low-level output.

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



 $^{^{\}ddagger}$ All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25 \,^{\circ}\text{C}$.

[§] Not more than one output should be shorted at a time.

¹ Average per flip-flop.

recommended operating conditions

			SI	N54LS7	3A	SI	174LS7	3A	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
ViH	High-level input voltage		2			2			٧
VIL	Low-level input voltage				0.7			0.8	V
Іон	High-level output current				- 0.4			- 0.4	mA
lOL	Low-level output current				4			8	mA
fclock	Clock frequency		0		30	0		30	MHz
	Pulse duration	CLK high	20			20			
t _W	ruise duration	CLR low	25			20			กร
	Con an almost had not Ol 161	data high or low	20			20			
t _{su}	Set up time-before CLK4	CLR inactive	20			20			ns
th	Hold time-data after CLK↓		0			0			ns
TA	Operating free-air temperature		- 55		125	0		70	°c

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	RAMETER		ST CONDITION	et	SI	N54LS73	3A	Si	N74LS7:	3A	UNIT
PA	ARAMETER		251 COMPITION	3.	MIN	TYP#	MAX	MIN	TYP#	MAX	UNIT
VIK		V _{CC} = MIN,	$t_1 = -18 \text{ mA}$				- 1.5			- 1.5	V
Voн		V _{CC} = MIN, I _{OH} = - 0.4 mA	V _{IH} = 2 V,	V _{IL} = MAX,	2.5	3.4		2.7	3.4		٧
\/ - ·		V _{CC} = MIN, I _{OL} = 4 mA	V _{IL} = MAX,	V _{IH} = 2 V,		0.25	0.4		0.25	0.4	V
VOL		V _{CC} = MIN, I _{OL} = 8 mA	VIL = MAX,	V _{IH} = 2 V,					0.35	0.5	v
	J or K						0.1			0.1	
l _l	CLR	V _{CC} = MAX,	V ₁ = 7 V				0.3			0.3	mA
	CLK						0.4			0.4	
	J or K	-					20			20	
чн	CLR	V _{CC} = MAX,	V ₁ = 2.7 V				60			60_	μА
	CLK						80			80	
	J or K	V	V = 0.4.V				0.4			- 0,4	mA
11L	CLR or CLK	V _{CC} = MAX,	V = 0.4 V				- 0.8			- 0.8	IIIA
los\$		V _{CC} = MAX,	See Note 4		- 20		– 100	- 20		- 100	mA
ICC (T	otai)	V _{CC} = MAX,	See Note 2			4	6		4	6	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	Mir	i TYP	MAX	UNIT
f _{max}				3	45		MHz
tPLH	CLR or CLK	Q or Q	$R_{\perp} = 2 k\Omega$, $C_{\perp} = 15$	i pF	15	20	ns
tPHL	CER OF CER	Q or Q			15	20	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ} \text{C}$.

[§] Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 2: With all outputs open, I_{CC} is measured with the Q and Q outputs high in turn. At the time of measurement, the clock input is grounded.

NOTE 4: For certain devices where state commutation can be caused by shorting an output to ground, an equivalent test may be performed with V_O = 2.25 V and 2.125 V for the 54 family and the 74 family, respectively, with the minimum and maximum limits reduced to one half of their stated values.



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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9675101QCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9675101QC A SNJ54LS73AJ	Samples
5962-9675101QDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9675101QD A SNJ54LS73AW	Samples
5962-9675101QDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9675101QD A SNJ54LS73AW	Samples
SN54LS73AJ	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS73AJ	Samples
SN54LS73AJ	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS73AJ	Samples
SN74LS73ADR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS73A	Samples
SN74LS73ADR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS73A	Samples
SN74LS73AN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS73AN	Samples
SN74LS73AN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS73AN	Samples
SN74LS73ANE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS73AN	Samples
SN74LS73ANE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS73AN	Samples
SNJ54LS73AJ	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9675101QC A SNJ54LS73AJ	Samples
SNJ54LS73AJ	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9675101QC A SNJ54LS73AJ	Samples
SNJ54LS73AW	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9675101QD A SNJ54LS73AW	Samples
SNJ54LS73AW	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9675101QD A	Samples

PACKAGE OPTION ADDENDUM

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Orderable Device	Status	Package Type	Package Drawing	Pins Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing	٦.,	(2)	(6)	(3)		(4/3)	
									SNJ54LS73AW	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54LS73A, SN74LS73A:

Catalog: SN74LS73A

PACKAGE OPTION ADDENDUM

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Military: SN54LS73A

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS73ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Ì	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ı	SN74LS73ADR	SOIC	D	14	2500	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9675101QDA	W	CFP	14	25	506.98	26.16	6220	NA
SN74LS73AN	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS73AN	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS73ANE4	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS73ANE4	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54LS73AW	W	CFP	14	25	506.98	26.16	6220	NA

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
 Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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